

## Introduction of CYTOP S type adhesion method (for spin coating)

### Precautions for handling

Please be sure to read MSDS before using this product to ensure safe handling.

The CYTOP S type has excellent mold release.  
If it is applied directly to a substrate, it can be peeled off easily.  
To attach the S type to a substrate, the following processing method is recommended.

1

Apply silane coupling agent \*1 and perform spin coating.

Spin condition: 500 rpm for 15 sec. + 4000 rpm for 20 sec.



\*1 Silane coupling agent  
"KBE-903" by Shin-Etsu Chemical Co., Ltd.  
"SILA-ACE S330" by Chisso Corporation, etc.

2

CTL-809A is diluted to 0.5% and spin coating is performed.

Spin conditions: 500 rpm for 5 sec. + 1000 rpm for 30 sec.



3

50°C x 30 min. baking

It must be stopped in a semi-dry condition. (If it is completely dry, adhesive power is low.)



4

CTX-809SP2 is diluted to 5% and spin coating is performed.

Spin condition: 500 rpm for 5 sec. + 1000 rpm for 30 sec.



5

Drying at room temperature: 5 to 30 min.

(Prebaking [degas]: 50°C x 10 to 30 min.)

\* If the film is thin (5 μm or less), this process is not required.

Prebaking [removal of solvent]: 80°C x 30 to 60 min.

Final baking: 180 to 250°C x 30 to 60 min.